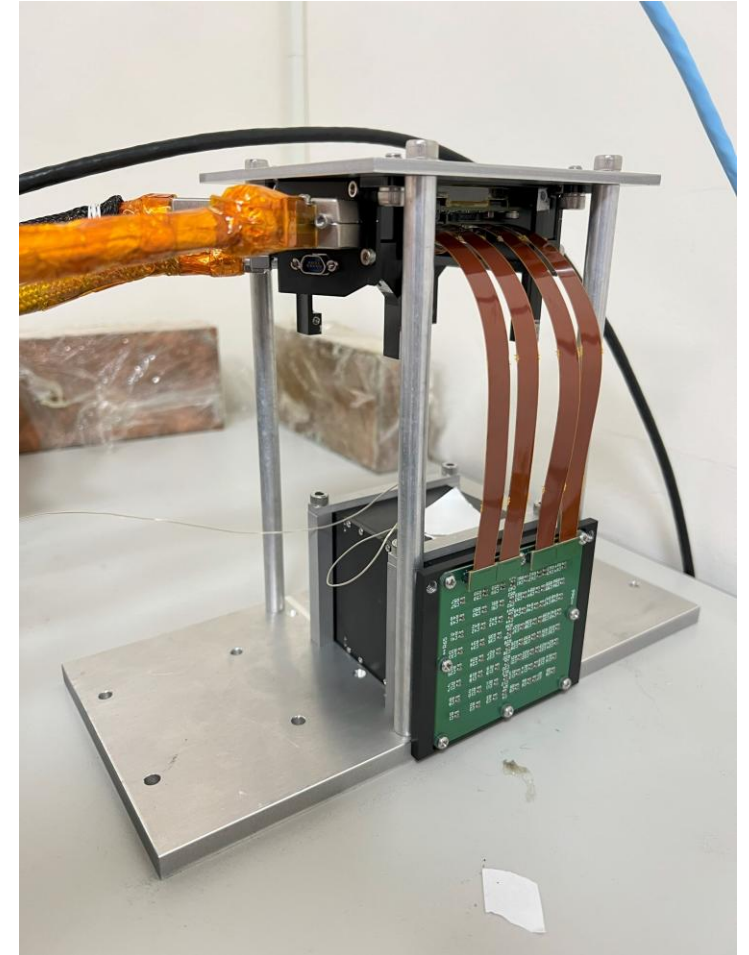


ePIC ZDC ECAL Prototype Hardware and AC-LGAD

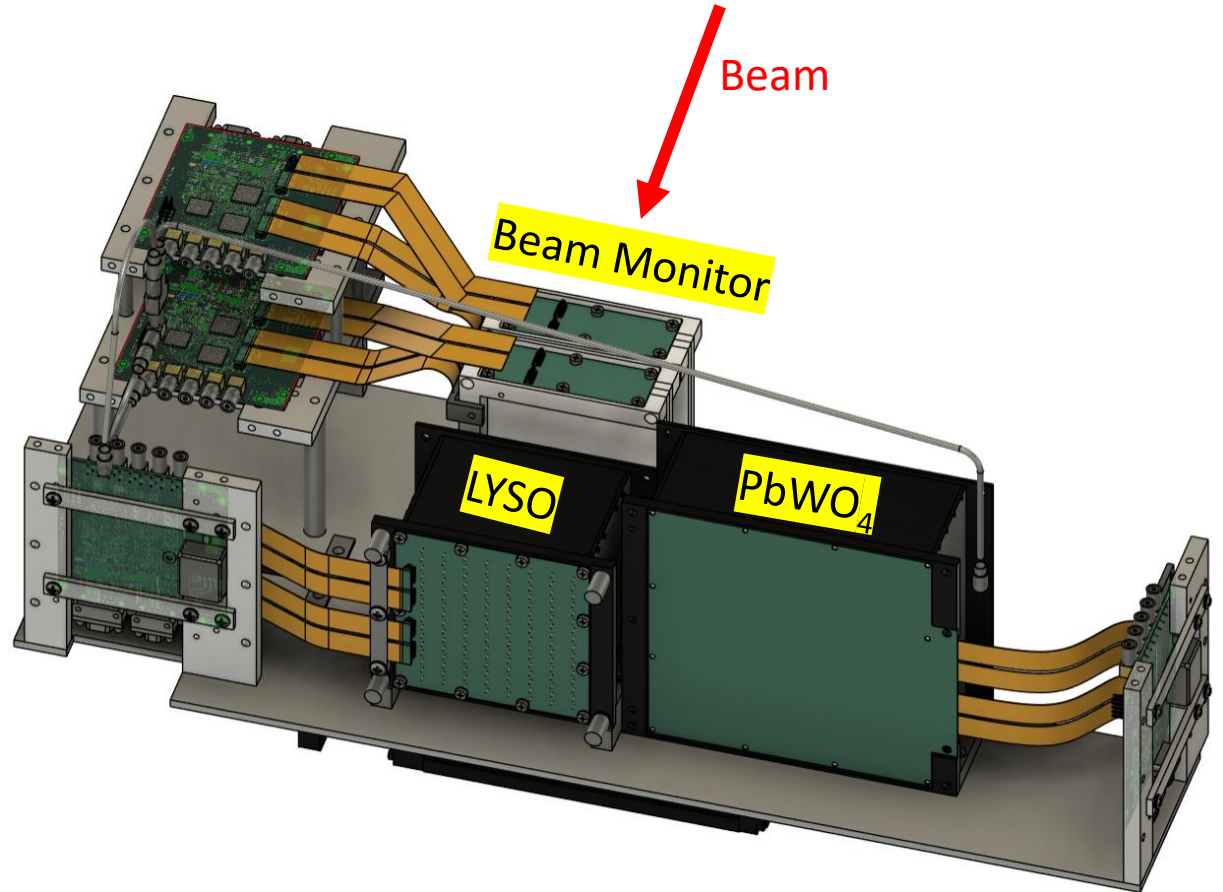
Cheng Kai-Yu

Institute of Physics, Academia Sinica, Taiwan

- **LYSO**
 - 8x8 array
 - Each crystal : 7.1mm*7.1mm*88.3mm ($8X_0$)
- **SiPM**
 - MICROFC-60035
 - 6x6 mm² sensitive area
- **Gamma-ray Transients Monitor (GTM) Readout board**
 - 2 Citiroc1A (2 x 32 channels)
 - Peak sensing mode
- ~12% energy resolution at 50MeV
- Obviously non-linear relation when energy larger than 50MeV
- (Show in Chia-Yu report)

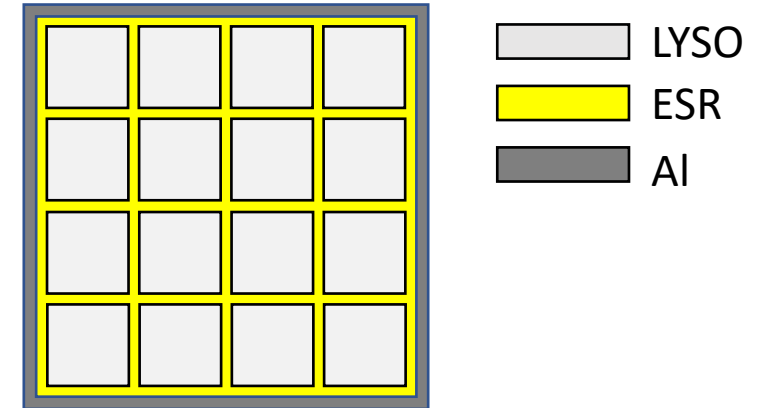


- **LYSO crystal:**
 - 8x8 array
 - APD readout
 - **PbWO₄ crystal:**
 - 6x6 array
 - SiPM readout
 - **Beam monitor x 2:**
 - 32 scintillator strip x 4
 - 2 X-Y monitor
- Each of the four detectors acquires data independently and synchronizes timing using a 20 Hz clock.
- LYSO + APD energy resolution ~35%
- PbWO₄ + SiPM energy resolution ~15%



8 × 8 Crystal Array

- Crystal size: 1 cm × 1 cm × 6.6 cm (6 X₀)
- Light yield: ≈ 33k photons/MeV (≈100 × PbWO₄)
- Each crystal is wrapped with ESR on five sides
- A 4 × 4 crystal array forms one tower, wrapped with aluminum foil
- Four towers in total



APD (C30739ECERH)

- Activate area : 5.6 x 5.6 mm²
- Operating Voltage : 400V
- Gain : x 100 (≈ 1/10000 x SiPM)
- Quantum efficiency : 80% at 430nm

APD operating voltage

APD Bias Difference

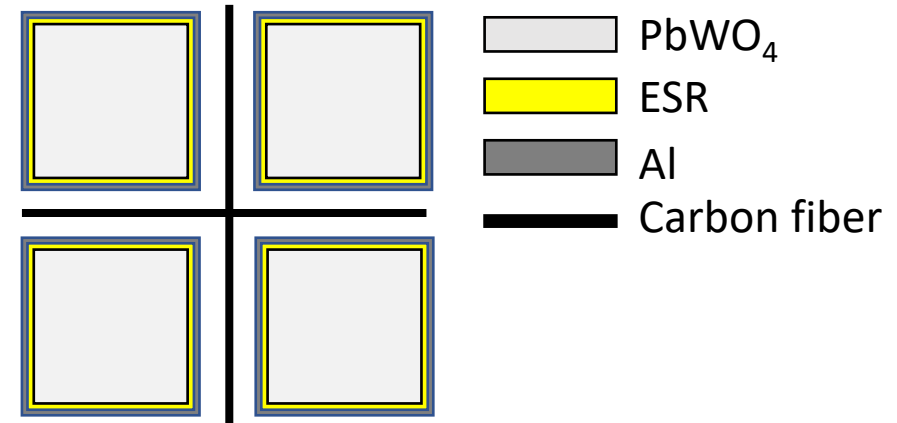
394.5	391.4	390.3	389.4	382.5	381.6	390.8	392.3	8.5	5.4	4.3	3.4	-3.5	-4.4	4.8	6.3
390.3	384.1	384.8	383.8	387.5	384.2	382.3	379.4	4.3	-1.9	-1.2	-2.2	1.5	-1.8	-3.7	-6.6
382.8	385.3	386.7	386.5	386.7	385.2	382.8	379.9	-3.2	-0.7	0.7	0.5	0.7	-0.8	-3.2	-6.1
389	385.3	386.3	385.9	386.1	385.3	389.2	392.4	3	-0.7	0.3	-0.1	0.1	-0.7	3.2	6.4
389.2	387.1	386.6	385.6	385.3	385.1	389.5	379.4	3.2	1.1	0.6	-0.4	-0.7	-0.9	3.5	-6.6
382.3	388.9	384.7	386.6	384.3	388.7	389.6	380.8	-3.7	2.9	-1.3	0.6	-1.7	2.7	3.6	-5.2
381	394.7	381.3	382.7	381.8	381.6	391.2	392.2	-5	8.7	-4.7	-3.3	-4.2	-4.4	5.2	6.2
394.5	393.9	393.6	392.6	393.4	393.7	394	393.9	8.5	7.9	7.6	6.6	7.4	7.7	8	7.9

6x6 PbWO₄ Crystals

- Bar Size : 2cm*2cm*5.3cm(6X0)
- Light yield : 300
- Each crystal is wrapped with ESR and aluminum foil on five sides.
- Each Crystal bar has two SiPM sensor
- The two SiPMs on the central crystal are read out separately
- The corner crystals use combined readout.

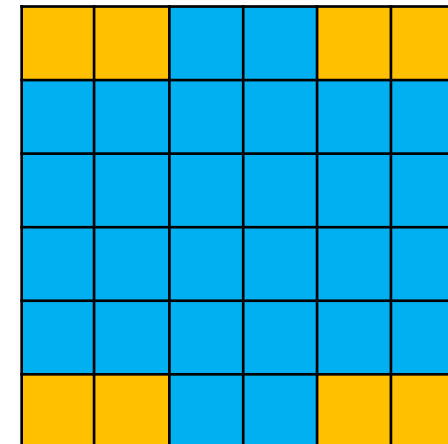
SiPM (ONSEMI MICROC-60035)

- Activate area : 6 x 6 mm²
- Breakdown Voltage : 24V
- Gain : > 10⁶
- Photon detection efficiency (PDE) : 41% at 430nm



■ 2 sensors separated readout

■ 2 sensors combined readout



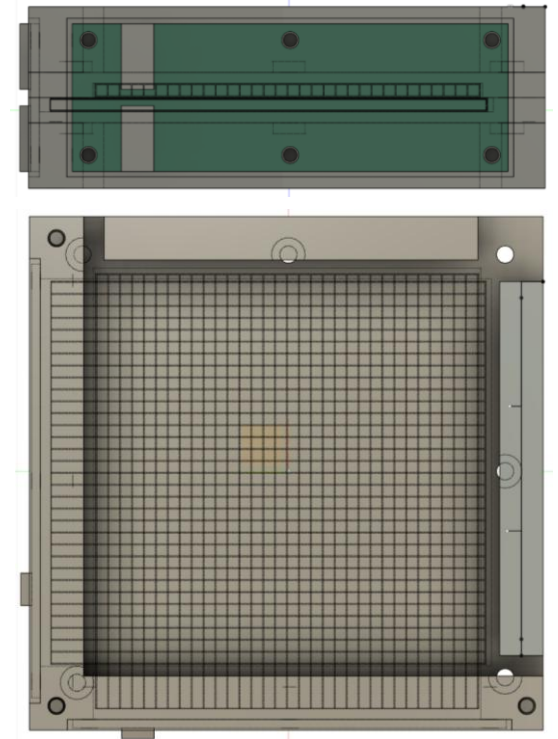
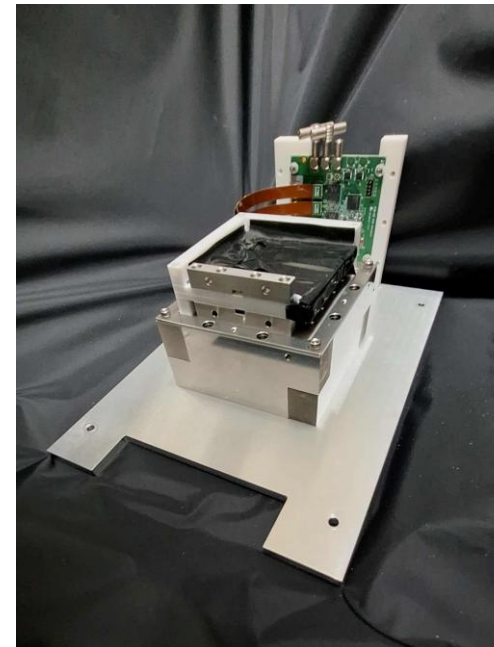
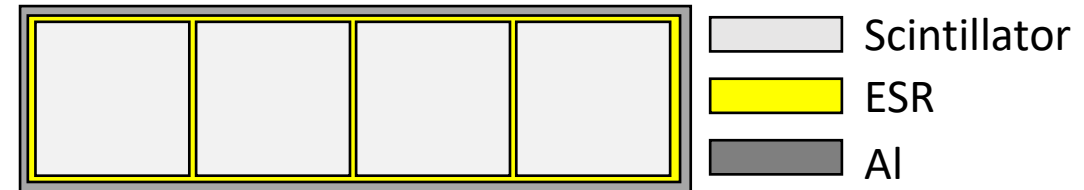
X-axis: 32 scintillator bars

Y-axis: 32 scintillator bars

- Bar size: 2 mm × 2 mm × 75 mm
- The monitors cover a 5 × 5 region in the LYSO array and a 3 × 3 region in the PbWO₄ array.
- Each bar is wrapped with ESR
- A 1 × 32 scintillator bar array is wrapped with aluminum foil
- Two X–Y position monitors are installed

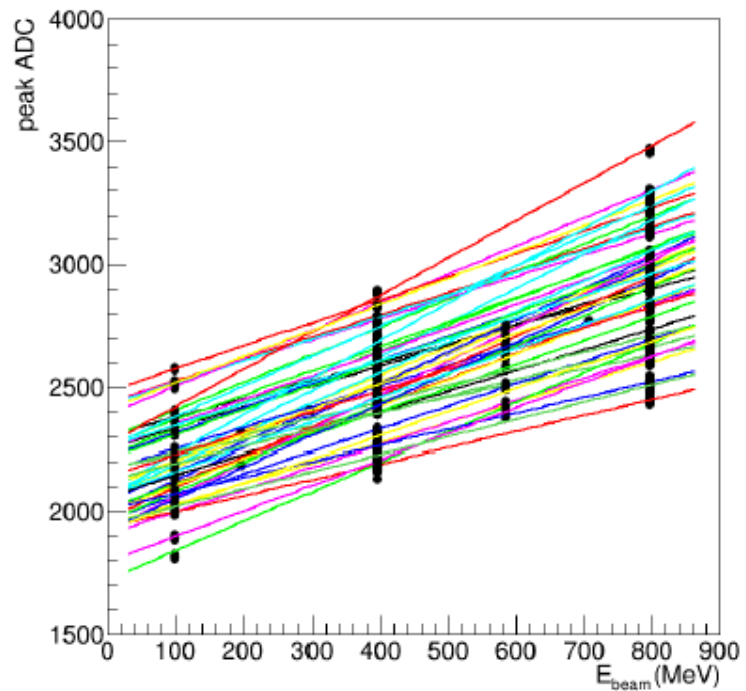
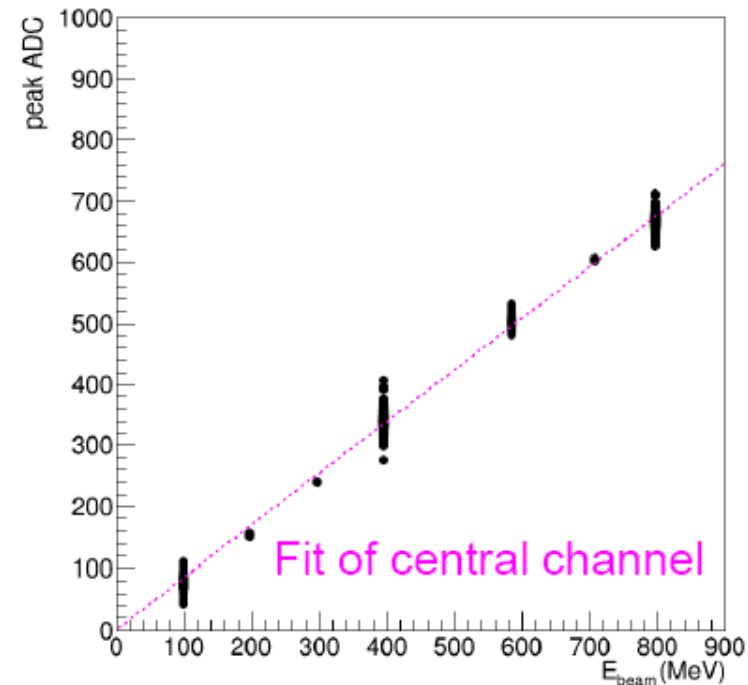
SiPM (ONSEMI MICROC-10020)

- Activate area : 1 x 1 mm²
- Breakdown Voltage : 24V
- Gain : > 10⁶
- Photon detection efficiency (PDE) : 41% at 430nm



Calibration procedure:

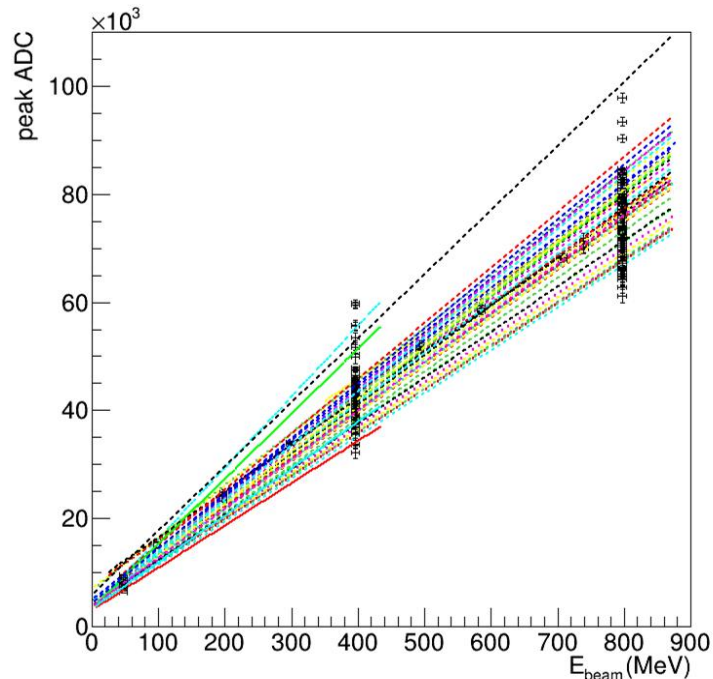
The beam energy was varied to scan all channels in the 5×5 crystal array. The gain of each channel was then adjusted (scaled and shifted) so that its response aligned with that of the central channel.

Before Gain Calibration**After Gain Calibration**

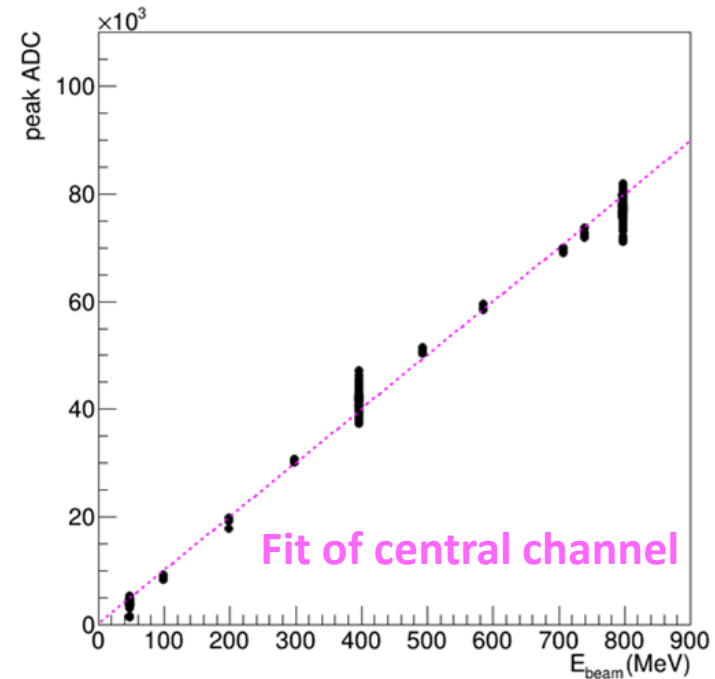
Calibration procedure:

The beam energy was varied to scan all channels in the 3×3 crystal array. The gain of each channel was then adjusted (scaled and shifted) so that its response aligned with that of the central channel.

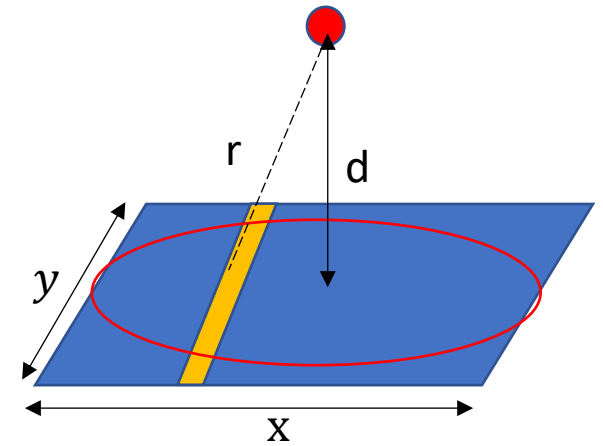
Before Gain Calibration



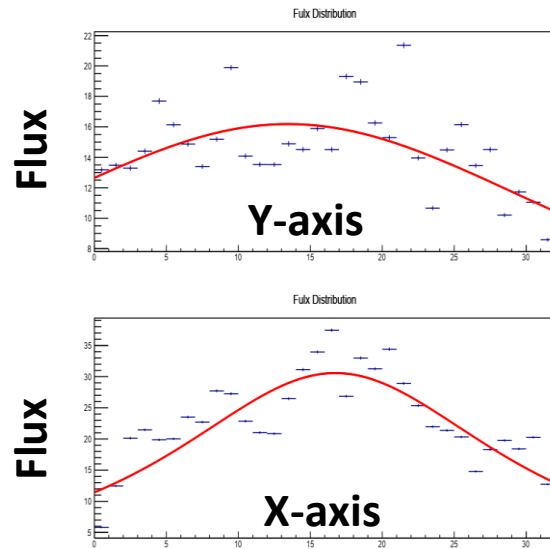
After Gain Calibration



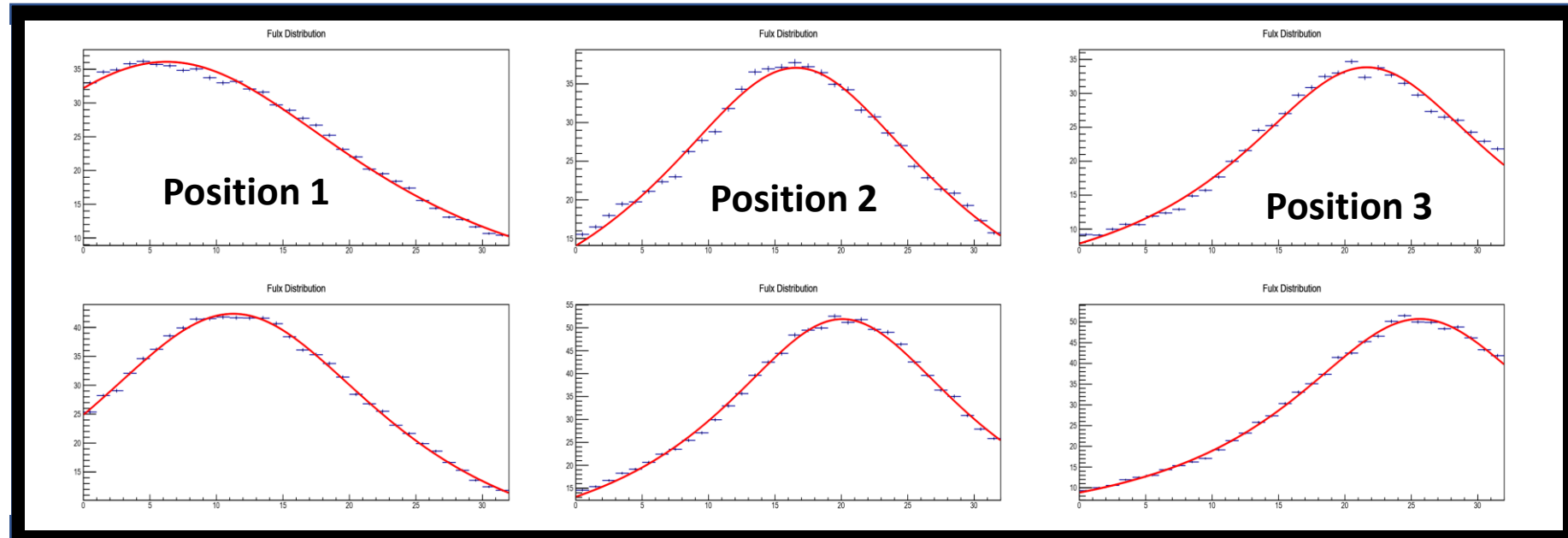
- Using flux of ^{22}Na source to do the beam monitor calibration.
- Channel flux $\propto \Omega \propto \iint \frac{d}{((x-x_0)^2+(y-y_0)^2+d^2)^{3/2}} dx dy$
- Flux distribution results with source placed at different positions after calibration



Before Calibration



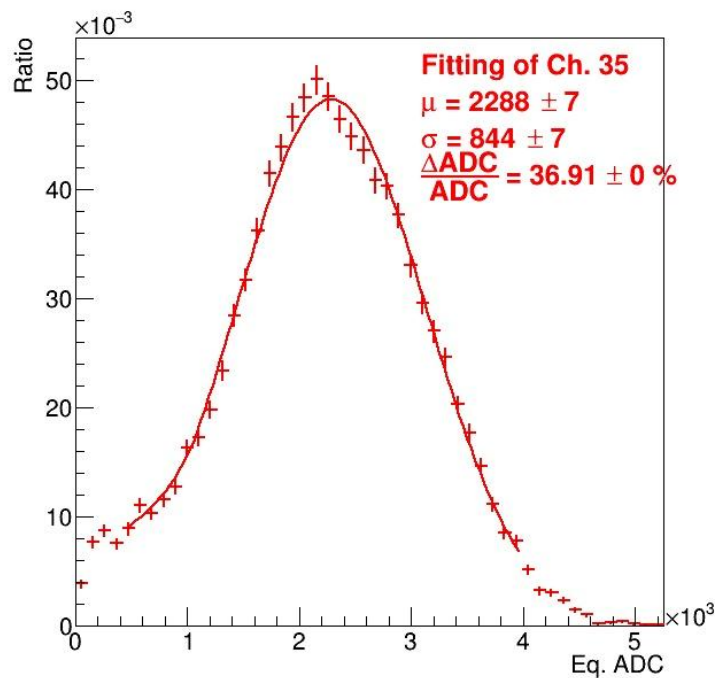
After Calibration



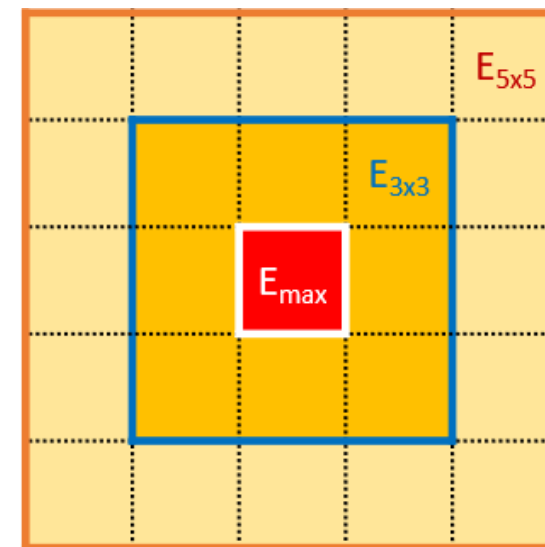
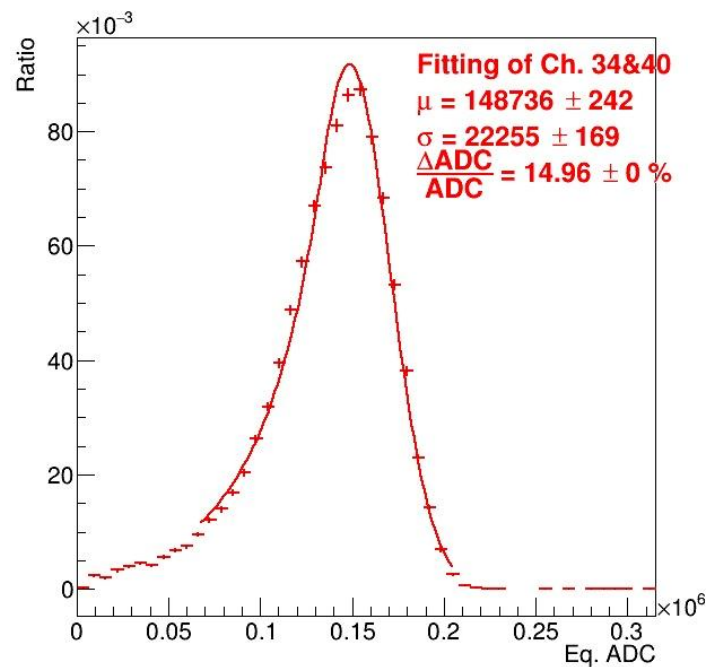
Energy spectrum from summed ADC values using 5×5 (LYSO) and 3×3 (PbWO₄) clustering after gain calibration.

~~✗~~ No energy regression applied.

LYSO 706MeV



PbWO₄ 706MeV



2nd Prototype ZDC ECal

- Cosmic Ray Study
- Noise Study

3rd Prototype ZDC ECal

- Using H2GCROC DAQ.
- Change to Hamamatsu S141603010 SiPM for LYSO Crystal
Higher micro pixels density => higher dynamic range
- Change to Hamamatsu S141603015 SiPM for PbWO4 Crystal
Number of pixels are lower than S141603010, but has higher PDE => better choice for PbWO4

Maximum Energy Estimate for 3rd Prototype :

$$3010PS: E_{max} = \frac{89984 \text{ pixels} * 0.7(\text{Linear range})}{18\% (\text{PDE}) * \text{collected ratio}} * \frac{10 * 10 \text{mm}^2}{3 * 3 \text{mm}^2} * \frac{1}{33\text{k} (\text{Photons/MeV})} \geq 117.8 \text{ MeV} \Rightarrow E_{beam} = \frac{117.8 \text{ MeV}}{39\%} \geq \mathbf{302 \text{MeV}}$$

$$3015PS: E_{max} = \frac{39984 \text{ pixels} * 0.7(\text{Linear range})}{32\% (\text{PDE}) * \text{collected ratio}} * \frac{20 * 20 \text{mm}^2}{3 * 3 \text{mm}^2} * \frac{1}{300 (\text{Photons/MeV})} \geq 13.0 \text{ GeV} \Rightarrow E_{beam} = \frac{1.30 \text{ GeV}}{45\%} \geq \mathbf{28.9 \text{GeV}}$$



ePIC ZDC ECAL Prototype Hardware
and
AC-LGAD

Cheng Kai-Yu

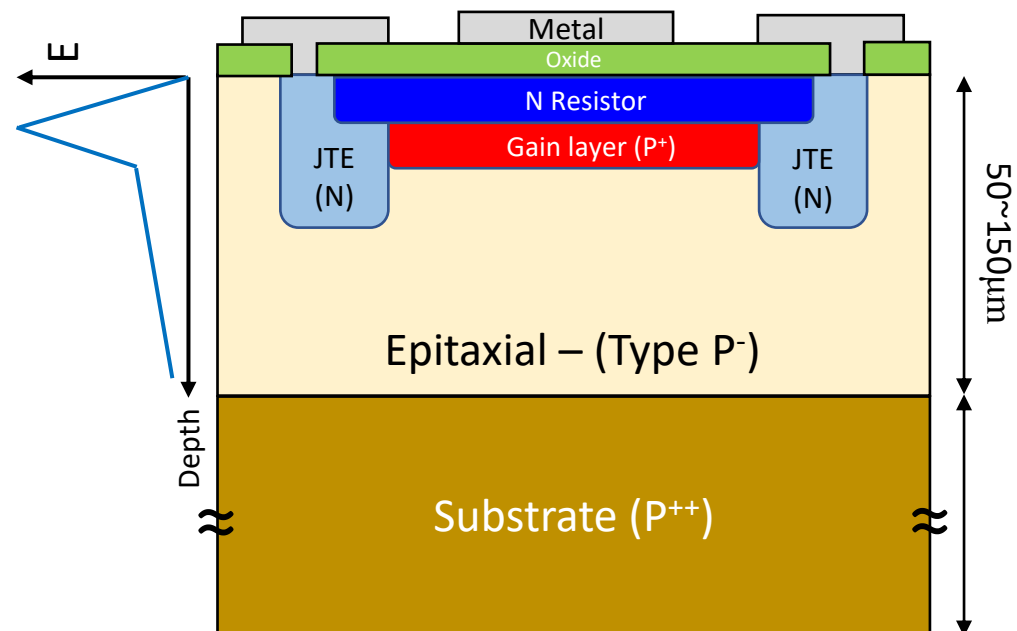
Project Objectives

- Partner with Brookhaven National Laboratory (BNL) to establish AC-LGAD production capability in Taiwan for the Electron-Ion Collider (EIC).
- Develop a localized particle sensor production line and learn fabrication expertise.

Project Progress

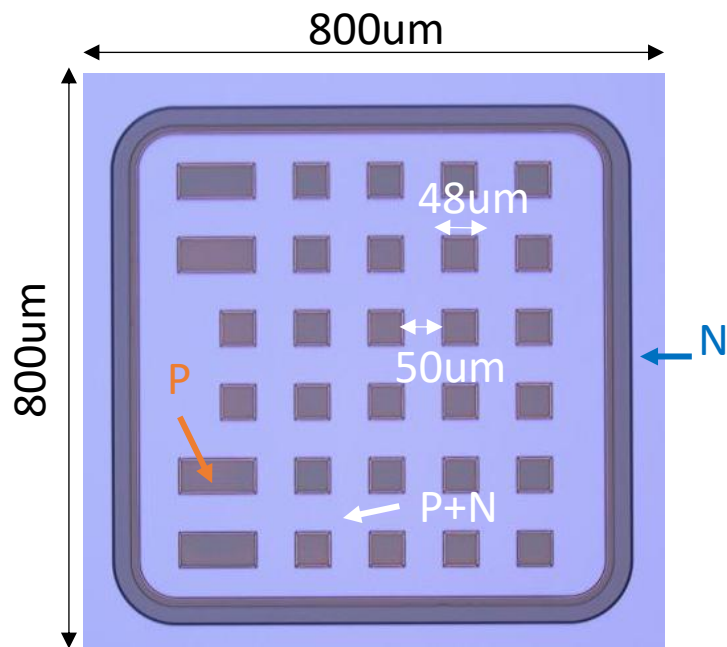
- Identified two foundries with process capabilities aligning with BNL requirements.
 - 鼎元光電 (Tyntek)
 - 茂矽電子 (MOSEL)
- Completed initial process parameter verification at Tyntek.
 - Validated manufacturing capabilities for BNL technical review.
 - Provided baseline data for TCAD simulation calibration.

- **SIMS-based verification** of **gain-layer** formation and **n-type sheet resistance** process reliability
- Serves as a **simulation calibration reference**
- **Process Split:** One p-type and two n-type implant groups.
- **Four wafers per split**
- No electrode structures were included.

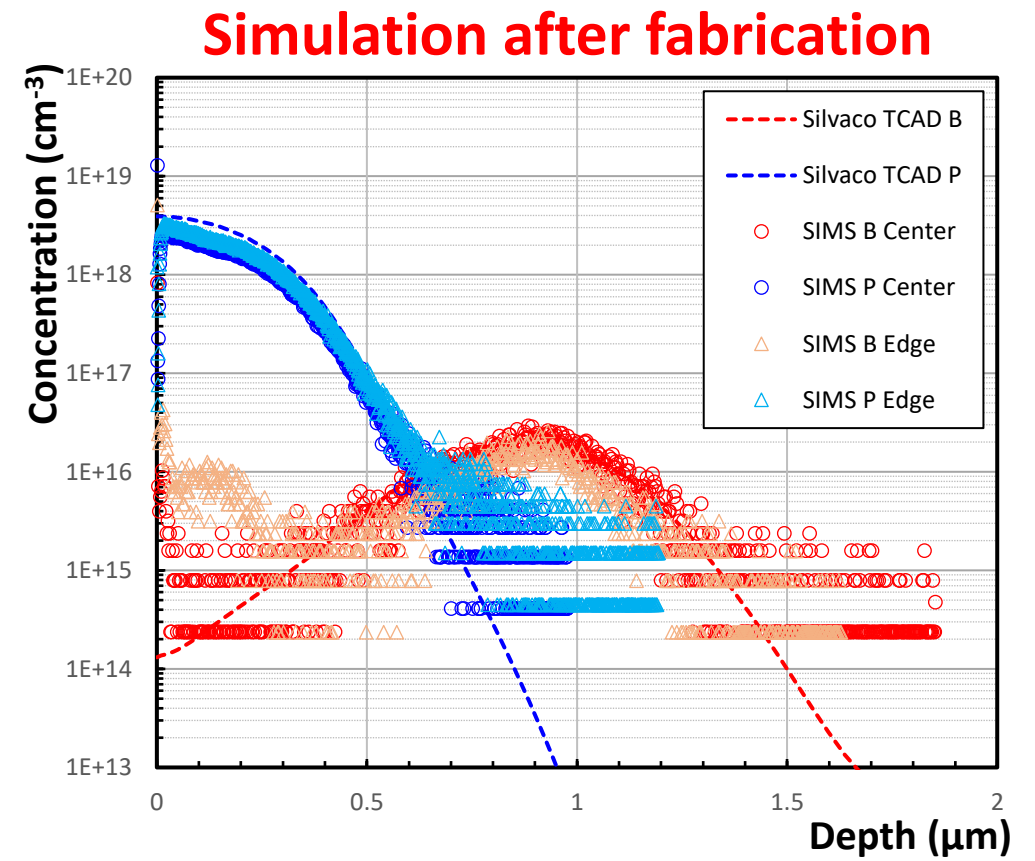
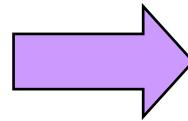
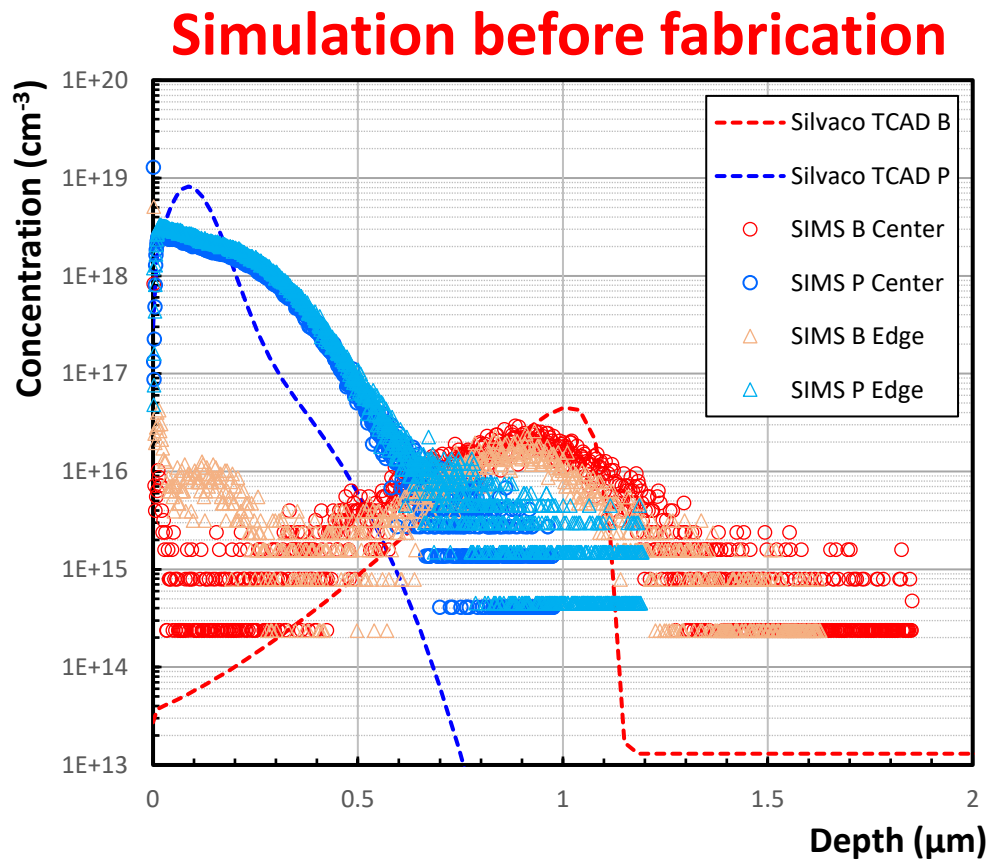


	Implant 1			Diffusion 1		Implant 2			Diffusion 2	
	impurities	Dose(cm ⁻²)	Energy	°C	min	impurities	Dose(cm ⁻²)	Energy	°C	min
#03-06	B	1.00E+12	380keV	800	20	As	1.00E+14	90keV	800	20
#07-10						P		80keV		

- For rapid process validation (non–full process), an in-house MOS test mask was adopted.
- Among the eight test wafers fabricated, the photomask patterns exhibited good clarity and uniformity.
- However, further optimization of the photoresist baking process is required to prevent minor localized exposure defects.

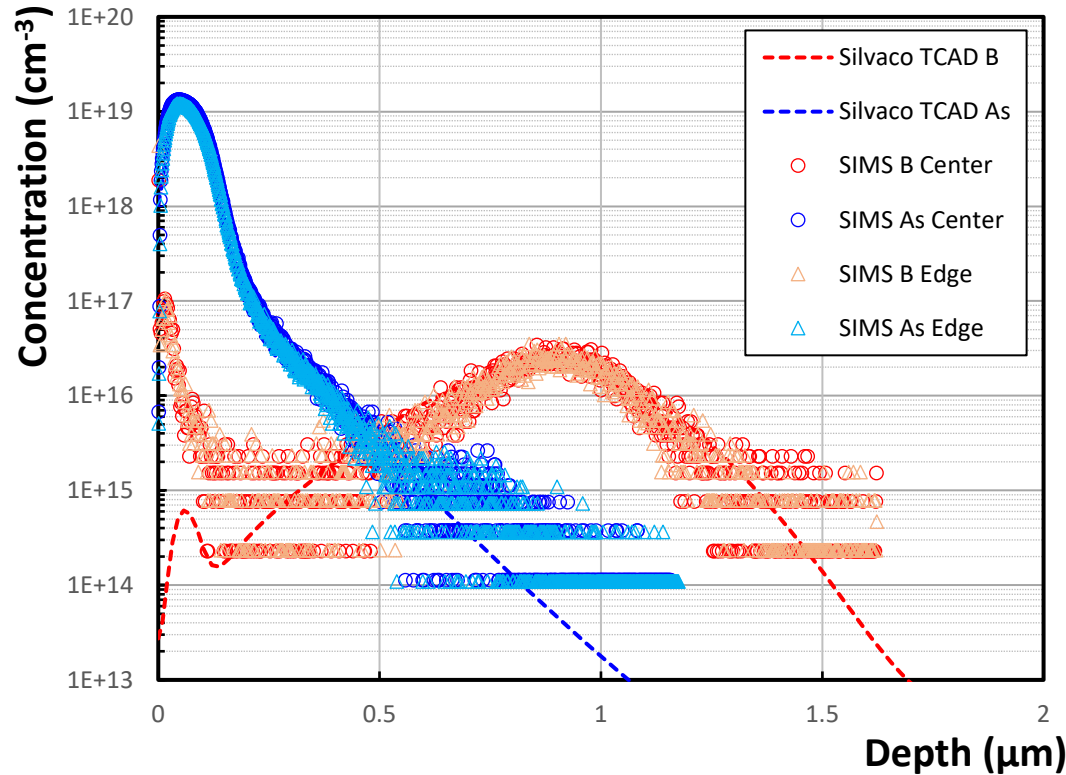


- Including implantation-induced damage in the simulation significantly improved agreement with the SIMS measurements.

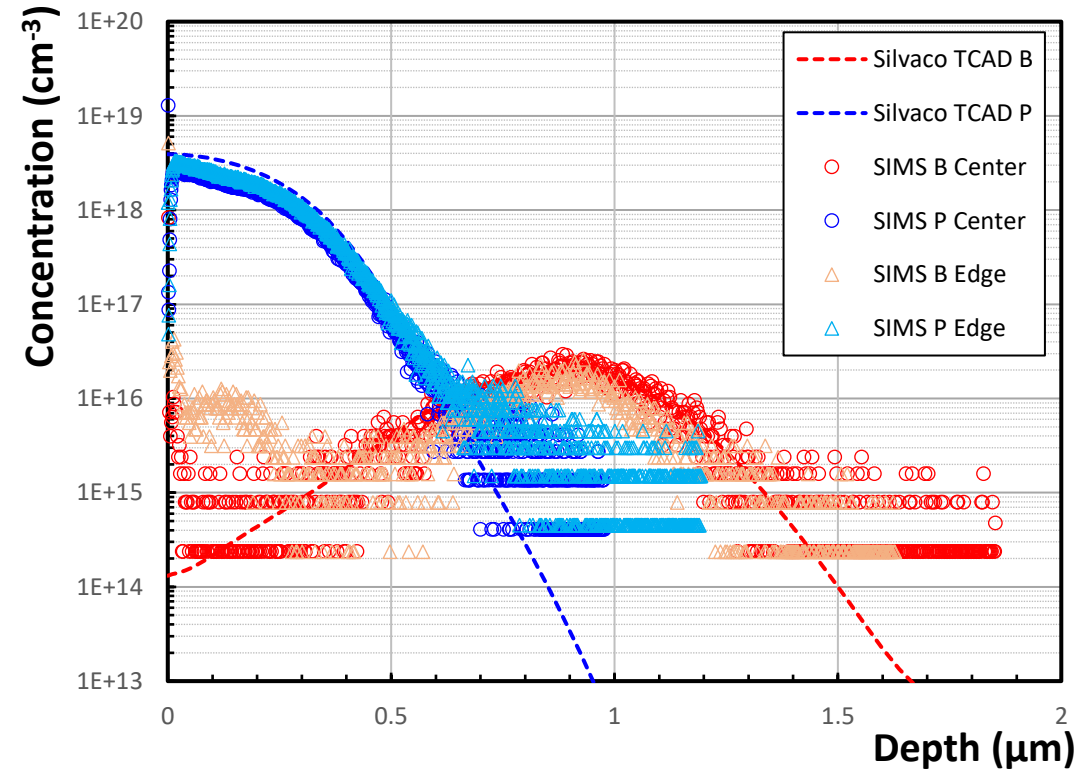


	Implant 1			Diffusion 1		Implant 2			Diffusion 2	
	impurities	Dose(cm ⁻²)	Energy	°C	min	impurities	Dose(cm ⁻²)	Energy	°C	min
#04	B	1.00E+12	380keV	800	20	As	1.00E+14	90keV	800	20
#10						P	1.00E+14	80keV		

Wafer #04 As + B



Wafer #10 P + B

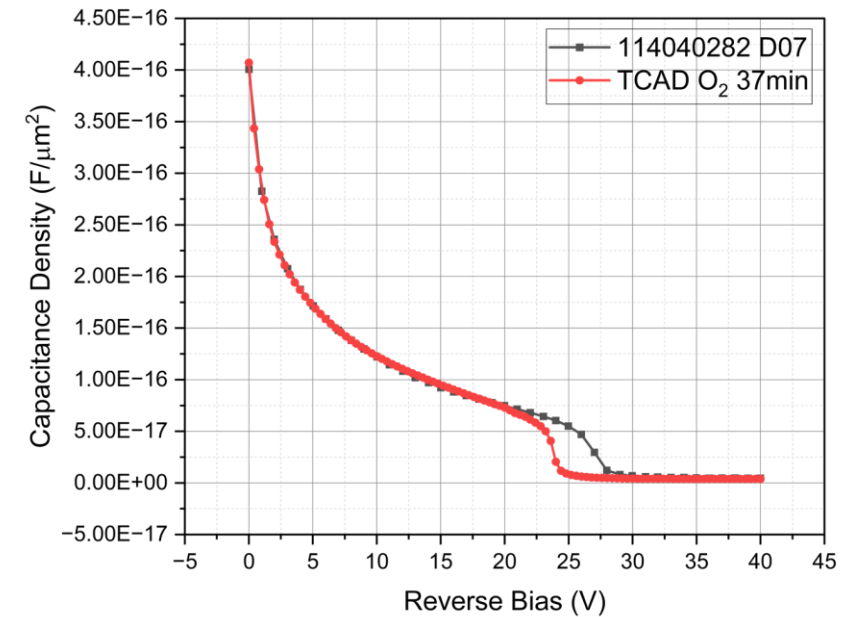
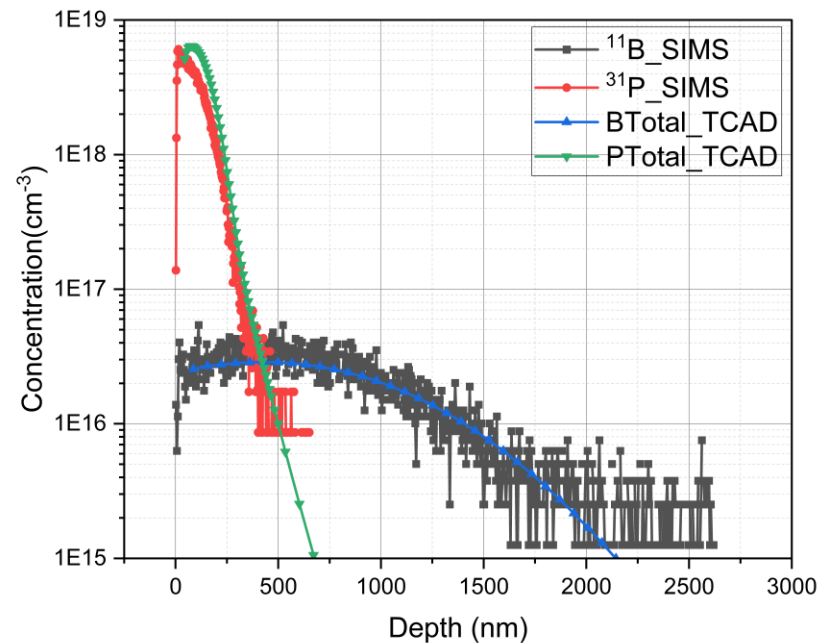
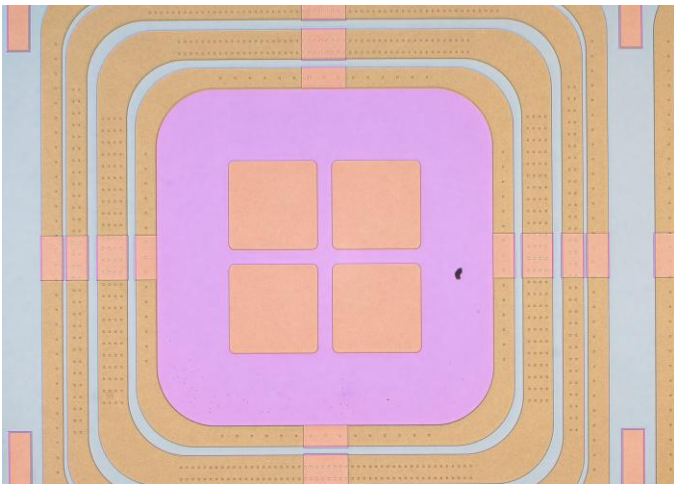


- After the test run, we received detailed full process technical documentation from BNL.
- We are currently discussing the full-process AC-LGAD fabrication with 鼎元光電 (Tyntek) and 茂矽電子 (MOSEL).
 - 6-inch EPI wafer processed using stepper masks
 - Process splits: AC coupling capacitor process and implant dose
- The first fabrication run is expected to begin in late January.
- The first run aims to directly compare with BNL sensors to benchmark the process status in Taiwan.
- Measurement Plan :
 - I–V and C–V characterization
 - LGAD gain measurement
 - n-type sheet resistance
 - RC coupling performance
 - SIMS analysis
- In later tests, different processes and other options will be studied.

Collaborator: Prof. I-Shan Lee (NTHU), Yu-Hsuan, Lee

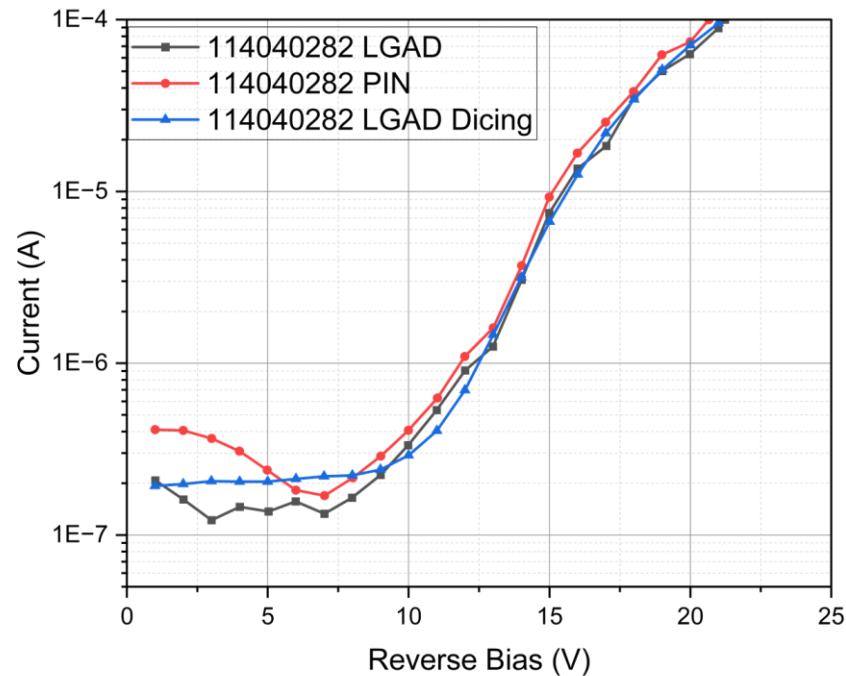
Objective: To obtain process know-how through hands-on AC-LGAD fabrication by students at TSRI. This experience will help us better understand how to adjust the process based on LGAD measurement results.

- Across three test runs, the students successfully resolved multiple process-related technical issues encountered at TSRI.
- The SIMS measurements and C–V curves show good agreement with TCAD simulation expectations.

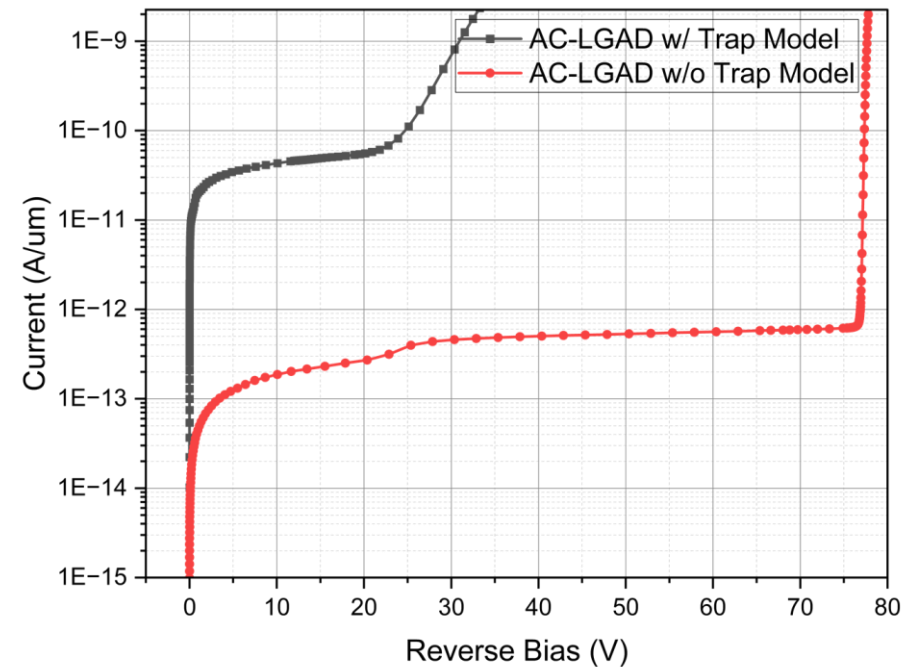


- Severe leakage current was observed in the TSRI samples during electrical testing, indicating the need for further process optimization.
- The leakage current issue may be related to D_{it} , defined as the trap density at the Si/oxide interface.
- Potential process adjustments are currently being investigated through TCAD simulations.

Sample Measurement



TCAD Simulation (w & w/o Trap Model)



ZDC Crystal ECal

- **In the second prototype, the detector system consisted of LYSO + APD, PbWO₄ + SiPM, and two position monitors.**
 - After gain calibration, the **energy resolution** was measured to be **35% for LYSO** and **15% for PbWO₄**, without applying energy regression.
- **A linear response was achieved for LYSO read out by APDs; however, the energy resolution degraded significantly.**
 - This issue is still under study and may be related to the APD operating conditions and readout configuration.
- **We're currently focusing on improving electronic noise performance.**
 - During the second beam test, the poor S/N ratio led to a loss of energy details.
 - The threshold level has been reduced to ~17 MeV, and stability tests are ongoing.
- **In the next version, the H2GCROC DAQ will be used together with high-density SiPMs from Hamamatsu.**
 - The expected dynamic range is up to ~28 GeV for PbWO₄ and ~300 MeV for LYSO.

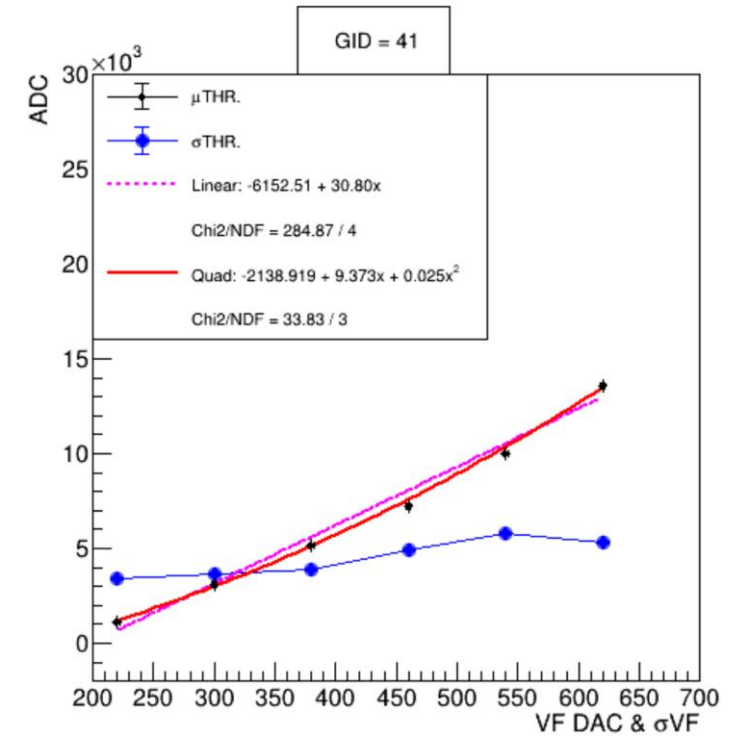
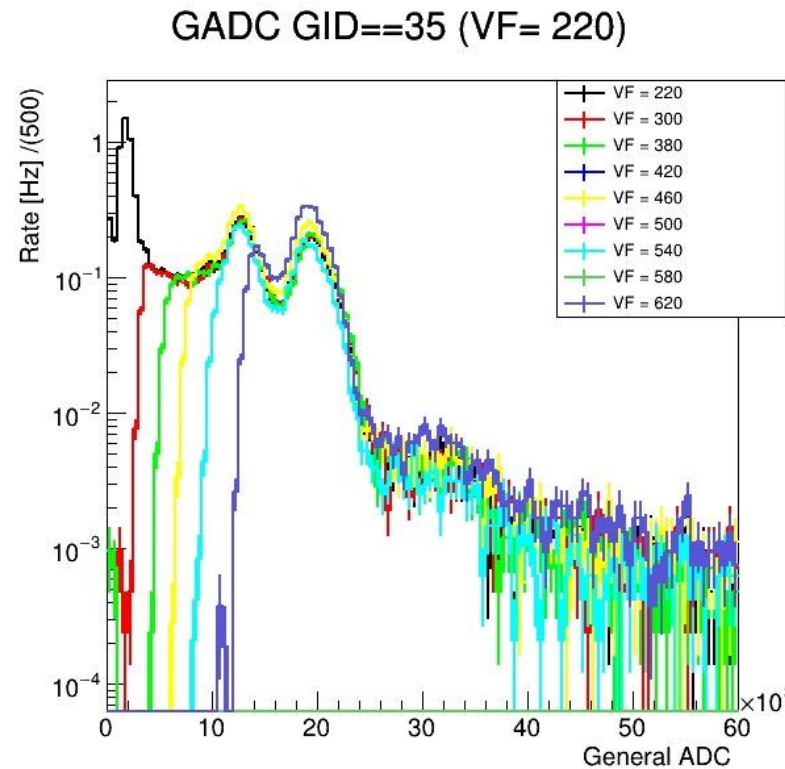
AC-LGAD

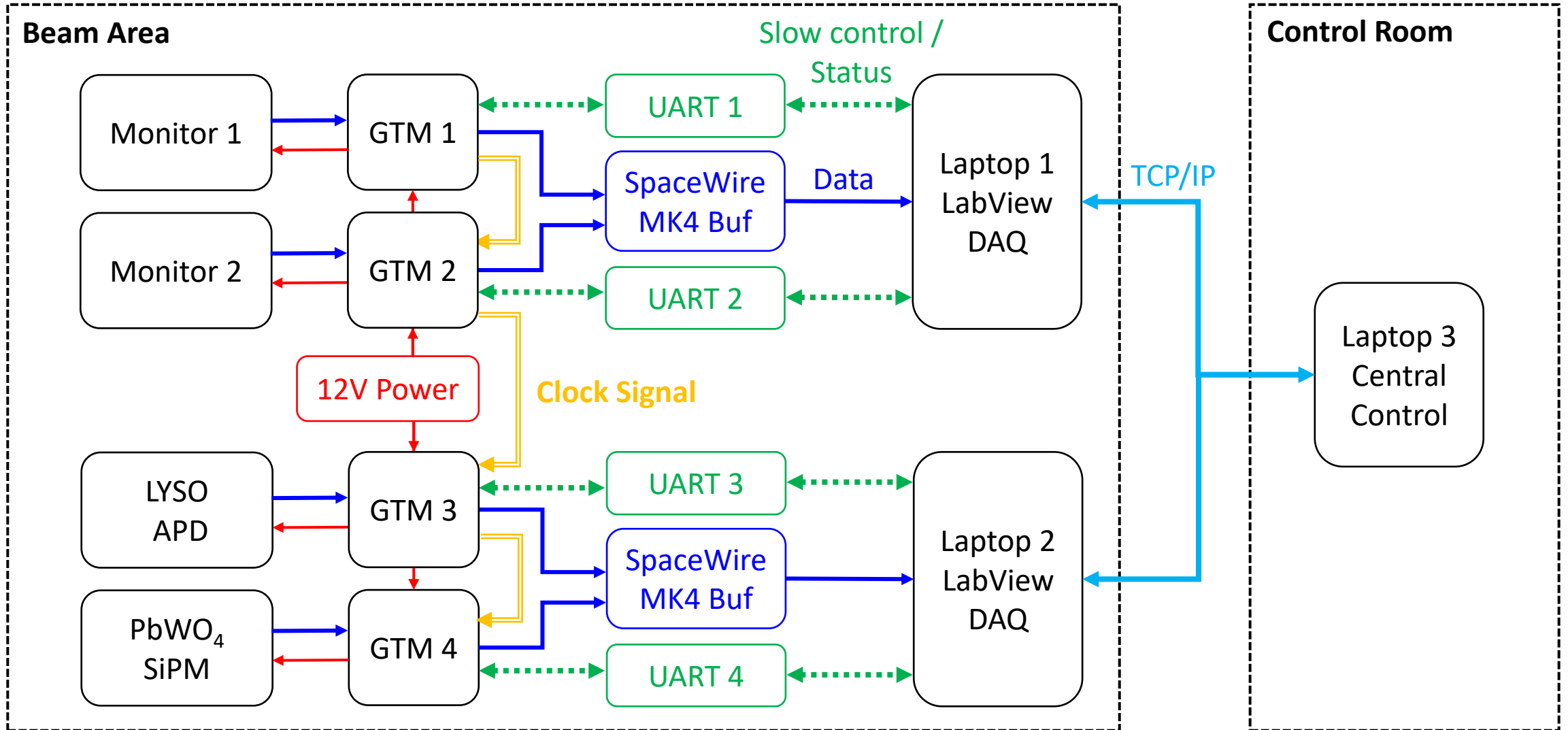
- **In collaboration with BNL, and based on BNL's experience in AC-LGAD development, we aim to establish an LGAD production line at 鼎元光電 (Tyntek) and 茂矽電子 (MOSEL).**
 - The goal is to produce a portion of the AC-LGAD sensors for the EIC.
- **Rapid process validation at Tyntek shows that implantation-induced damage must be included in simulations to achieve good agreement with experimental data.**
 - The damage behavior may be partly caused from the AC coupling oxide capacitor process, which will be included in test.
- **The full-process fabrication is in progress, aiming for a direct comparison with BNL AC-LGAD samples under identical process conditions.**
 - AC-LGAD samples from BNL have been received.
 - Next step : Establish the measurement system and characterization workflow based on BNL's recommendations.
- **Process studies are also ongoing at TSRI to support future LGAD analysis.**
 - Good agreement has been achieved in the doping profiles.
 - Large leakage current due to process-related issues is still under investigation through simulation tuning.



Back up

- Due to excessive system noise in the second experiment, a more stable GAGG+SiPM module was used to help study the relationship between threshold and voltage.
- The discriminator threshold setting of CITIROC is independent of the input signal and the module.
- Once the ADC cut corresponding to a given threshold DAC value is identified, the corresponding energy cut used in the beam test can be determined.

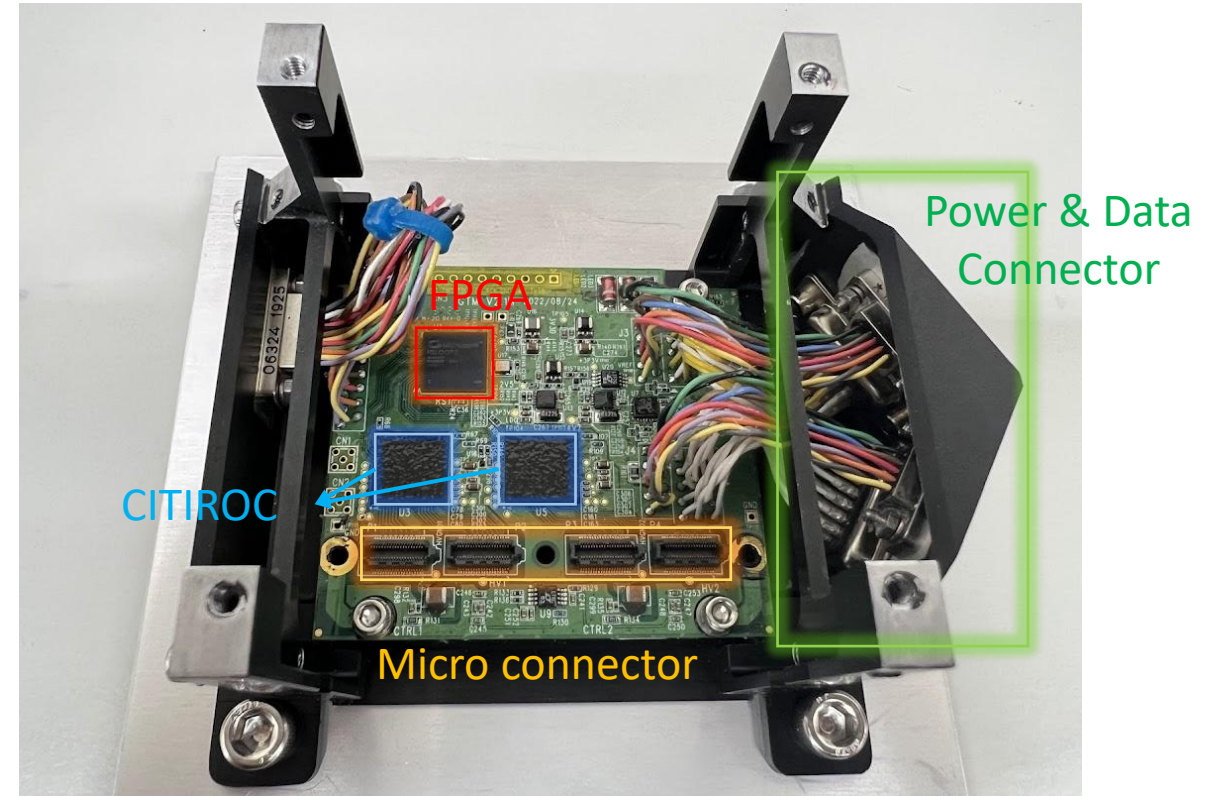




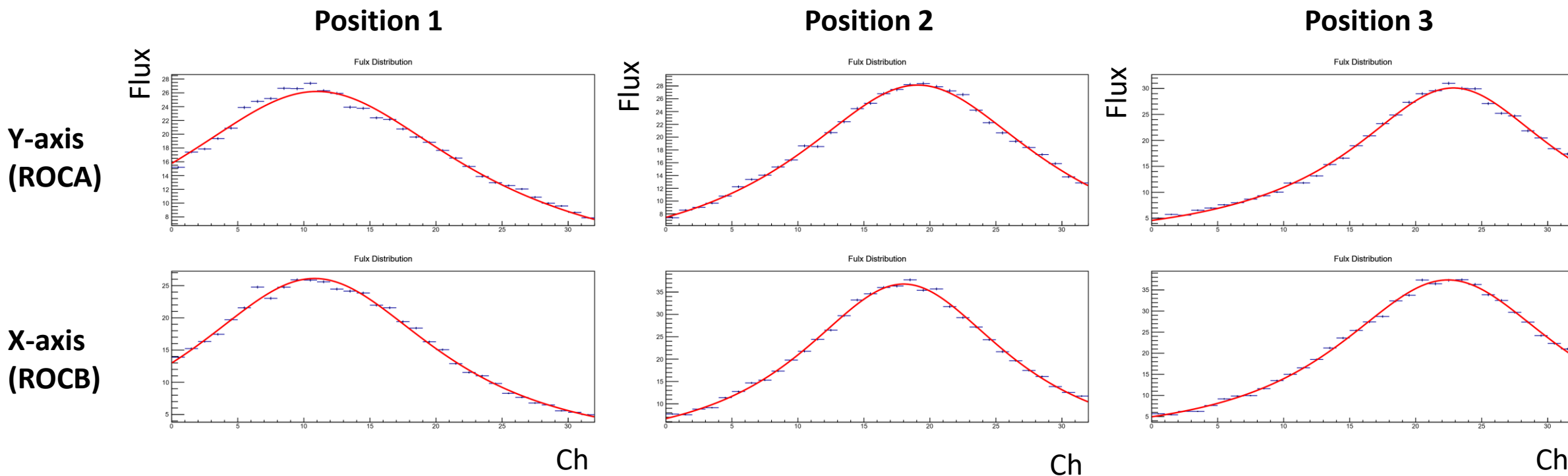
Gamma-ray Transients Monitor (GTM)

The SiPM array readout system for gamma-ray detector in other space experiment. It includes :

- FPGA chip
- 2 x CITIROC 1A ASIC = 2 x 32 channels
- 2 x High-voltage convertor for bias of SiPM
- Samtec Micro Blade & Beam connectors for SiPM interface (16 channels + HV + GND)
- SpaceWire data interface
- Self-Trigger mode
- Maximum taking rate : 40k Hz



- Flux distribution results with the ^{22}Na source placed at different positions under the same voltage setting.



- Electrical simulations were performed based on the corrected doping profiles.
- $Gain = Q_{generated} / Q_{Injected}$
- Due to variations in boron concentration, the **As + B** condition did not achieve sufficient gain.
- In contrast, the **P + B** case still showed adequate gain in the simulation.
- The n-type sheet resistance was $\sim 600 \Omega/\square$.

